Abstracts

A General Purpose 3D Electromagnetic Simulation and Optimization Package -- IE3D

J.-X. Zheng. "A General Purpose 3D Electromagnetic Simulation and Optimization Package -- IE3D." 1994 MTT-S International Microwave Symposium Digest 94.1 (1994 Vol. I [MWSYM]): 373-376.

A general propose electromagnetic simulation and optimization package IE3D has been developed for the analysis and design of planar and 3D structures encountered in microwave and millimeter-wave integrated circuits (MMIC), high temperature superconductor (HTS) circuits, microstrip antennas, RF printed circuit boards (PCB) and high speed digital circuit packaging. Based upon an integral equation, method of moment algorithm, the simulator can accurately and efficiently simulate arbitrarily shaped and oriented 3D metallic structures in multi-layer dielectric substrates. The simulator is interfaced with standard MS-Windows based layout editor, schematic editor and post processor. The IE3D simulation results compared with measured results will be presented in this paper.

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